

COVER LAYER ENCAPSULATED FLEXIBLE CIRCUIT

ABSTRACT OF THE DISCLOSURE

Embodiments of the present invention provide a flexible circuit at least partially  
5 encapsulated by a cover layer. The flexible circuit includes a substrate having one or  
more openings. One or more electrical conductors are bonded to the top surface of the  
substrate. A first cover layer is bonded to the top surface of the substrate and to the  
electrical conductors. A second cover layer is bonded to the bottom surface of the  
substrate and to the first cover layer through the openings.

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